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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Active
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I <sup>2</sup> C, IrDA, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	79
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	64K x 8
Voltage - Supply (Vcc/Vdd)	1.62V ~ 3.6V
Data Converters	A/D 17x10b; D/A 1x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-VFBGA
Supplier Device Package	100-VFBGA (7x7)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/atsam4n8ca-cfur">https://www.e-xfl.com/product-detail/microchip-technology/atsam4n8ca-cfur</a>

#### 11.4.1.17 Exceptions and Interrupts

The Cortex-M4 processor supports interrupts and system exceptions. The processor and the *Nested Vectored Interrupt Controller* (NVIC) prioritize and handle all exceptions. An exception changes the normal flow of software control. The processor uses the Handler mode to handle all exceptions except for reset. See “Exception Entry” and “Exception Return” for more information.

The NVIC registers control interrupt handling. See “Nested Vectored Interrupt Controller (NVIC)” for more information.

#### 11.4.1.18 Data Types

The processor supports the following data types:

- 32-bit words
- 16-bit halfwords
- 8-bit bytes
- The processor manages all data memory accesses as little-endian. Instruction memory and *Private Peripheral Bus* (PPB) accesses are always little-endian. See “Memory Regions, Types and Attributes” for more information.

#### 11.4.1.19 Cortex Microcontroller Software Interface Standard (CMSIS)

For a Cortex-M4 microcontroller system, the *Cortex Microcontroller Software Interface Standard* (CMSIS) defines:

- A common way to:
  - Access peripheral registers
  - Define exception vectors
- The names of:
  - The registers of the core peripherals
  - The core exception vectors
- A device-independent interface for RTOS kernels, including a debug channel.

The CMSIS includes address definitions and data structures for the core peripherals in the Cortex-M4 processor.

The CMSIS simplifies the software development by enabling the reuse of template code and the combination of CMSIS-compliant software components from various middleware vendors. Software vendors can expand the CMSIS to include their peripheral definitions and access functions for those peripherals.

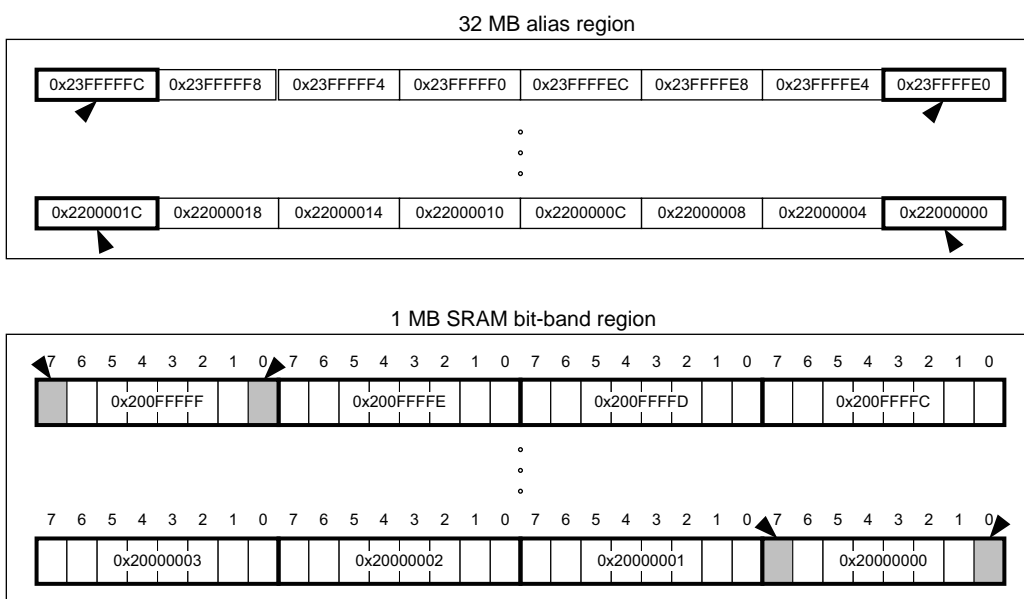
This document includes the register names defined by the CMSIS, and gives short descriptions of the CMSIS functions that address the processor core and the core peripherals.

Note: This document uses the register short names defined by the CMSIS. In a few cases, these differ from the architectural short names that might be used in other documents.

The following sections give more information about the CMSIS:

- Section 11.5.3 “Power Management Programming Hints”
- Section 11.6.2 “CMSIS Functions”
- Section 11.8.2.1 “NVIC Programming Hints”.

**Figure 11-4. Bit-band Mapping**



#### *Directly Accessing an Alias Region*

Writing to a word in the alias region updates a single bit in the bit-band region.

Bit[0] of the value written to a word in the alias region determines the value written to the targeted bit in the bit-band region. Writing a value with bit[0] set to 1 writes a 1 to the bit-band bit, and writing a value with bit[0] set to 0 writes a 0 to the bit-band bit.

Bits[31:1] of the alias word have no effect on the bit-band bit. Writing 0x01 has the same effect as writing 0xFF. Writing 0x00 has the same effect as writing 0x0E.

Reading a word in the alias region:

- 0x00000000 indicates that the targeted bit in the bit-band region is set to 0
- 0x00000001 indicates that the targeted bit in the bit-band region is set to 1

#### *Directly Accessing a Bit-band Region*

“Behavior of Memory Accesses” describes the behavior of direct byte, halfword, or word accesses to the bit-band regions.

#### **11.4.2.6 Memory Endianness**

The processor views memory as a linear collection of bytes numbered in ascending order from zero. For example, bytes 0-3 hold the first stored word, and bytes 4-7 hold the second stored word. “Little-endian Format” describes how words of data are stored in memory.

**Figure 11-5.**

#### *Little-endian Format*

In little-endian format, the processor stores the least significant byte of a word at the lowest-numbered byte, and the most significant byte at the highest-numbered byte. For example:

```

; with top halfword of R5, subtracts second from
; first, adds R6, writes to R0
SMLSDX R1, R3, R2, R0 ; Multiplies bottom halfword of R3 with top
; halfword of R2, multiplies top halfword of R3
; with bottom halfword of R2, subtracts second from
; first, adds R0, writes to R1
SMLSLD R3, R6, R2, R7 ; Multiplies bottom halfword of R6 with bottom
; halfword of R2, multiplies top halfword of R6
; with top halfword of R2, subtracts second from
; first, adds R6:R3, writes to R6:R3
SMLSLDX R3, R6, R2, R7 ; Multiplies bottom halfword of R6 with top
; halfword of R2, multiplies top halfword of R6
; with bottom halfword of R2, subtracts second from
; first, adds R6:R3, writes to R6:R3.

```

### 11.6.11 Miscellaneous Instructions

The table below shows the remaining Cortex-M4 instructions:

**Table 11-27. Miscellaneous Instructions**

Mnemonic	Description
BKPT	Breakpoint
CPSID	Change Processor State, Disable Interrupts
CPSIE	Change Processor State, Enable Interrupts
DMB	Data Memory Barrier
DSB	Data Synchronization Barrier
ISB	Instruction Synchronization Barrier
MRS	Move from special register to register
MSR	Move from register to special register
NOP	No Operation
SEV	Send Event
SVC	Supervisor Call
WFI	Wait For Interrupt

### 11.9.1.12 System Handler Control and State Register

**Name:** SCB\_SHCSR

**Access:** Read-write

**Reset:** 0x00000000

31	30	29	28	27	26	25	24
—							
23	22	21	20	19	18	17	16
—					USGFAULTENA	BUSFAULTENA	MEMFAULTENA
15	14	13	12	11	10	9	8
SVCALLPENDE D	BUSFAULTPEN DED	MEMFAULTPEN DED	USGFAULTPEN DED	SYSTICKACT	PENDSVACT	—	MONITORACT
7	6	5	4	3	2	1	0
SVCALLAVCT	—			USGFAULTACT	—	BUSFAULTACT	MEMFAULTACT

The SHCSR register enables the system handlers, and indicates the pending status of the bus fault, memory management fault, and SVC exceptions; it also indicates the active status of the system handlers.

- **USGFAULTENA: Usage Fault Enable**

0: Disables the exception.

1: Enables the exception.

- **BUSFAULTENA: Bus Fault Enable**

0: Disables the exception.

1: Enables the exception.

- **MEMFAULTENA: Memory Management Fault Enable**

0: Disables the exception.

1: Enables the exception.

- **SVCALLPENDED: SVC Call Pending**

Read:

0: The exception is not pending.

1: The exception is pending.

Note: The user can write to these bits to change the pending status of the exceptions.

- **BUSFAULTPENDED: Bus Fault Exception Pending**

Read:

0: The exception is not pending.

1: The exception is pending.

Note: The user can write to these bits to change the pending status of the exceptions.

## 13.4 Functional Description

### 13.4.1 Reset Controller Overview

The Reset Controller is made up of an NRST Manager and a Reset State Manager. It runs at Slow Clock and generates the following reset signals:

- `proc_nreset`: Processor reset line. It also resets the Watchdog Timer
- `periph_nreset`: Affects the whole set of embedded peripherals
- `nrst_out`: Drives the NRST pin

These reset signals are asserted by the Reset Controller, either on external events or on software action. The Reset State Manager controls the generation of reset signals and provides a signal to the NRST Manager when an assertion of the NRST pin is required.

The NRST Manager shapes the NRST assertion during a programmable time, thus controlling external device resets.

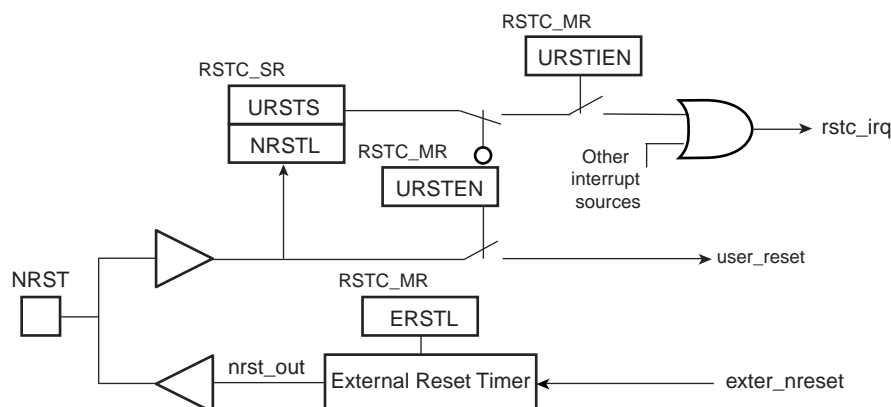
The Reset Controller Mode Register (RSTC\_MR), allowing the configuration of the Reset Controller, is powered with VDDIO, so that its configuration is saved as long as VDDIO is on.

### 13.4.2 NRST Manager

After power-up, NRST is an output during the ERSTL time period defined in the RSTC\_MR. When ERSTL has elapsed, the pin behaves as an input and all the system is held in reset if NRST is tied to GND by an external signal.

The NRST Manager samples the NRST input pin and drives this pin low when required by the Reset State Manager. Figure 13-2 shows the block diagram of the NRST Manager.

**Figure 13-2. NRST Manager**



#### 13.4.2.1 NRST Signal or Interrupt

The NRST Manager samples the NRST pin at Slow Clock speed. When the line is detected low, a User Reset is reported to the Reset State Manager.

However, the NRST Manager can be programmed to not trigger a reset when an assertion of NRST occurs. Writing the bit **URSTEN** at 0 in **RSTC\_MR** disables the User Reset trigger.

The level of the pin NRST can be read at any time in the bit **NRSTL** (NRST level) in **RSTC\_SR**. As soon as the pin NRST is asserted, the bit **URSTS** in **RSTC\_SR** is set. This bit clears only when **RSTC\_SR** is read.

The Reset Controller can also be programmed to generate an interrupt instead of generating a reset. To do so, the bit **URSTIEN** in **RSTC\_MR** must be written at 1.

## 20. Fast Flash Programming Interface (FFPI)

### 20.1 Description

The Fast Flash Programming Interface (FFPI) provides parallel high-volume programming using a standard gang programmer. The parallel interface is fully handshaked and the device is considered to be a standard EEPROM. Additionally, the parallel protocol offers an optimized access to all the embedded Flash functionalities.

Although the Fast Flash Programming Mode is a dedicated mode for high volume programming, this mode is not designed for in-situ programming.

### 20.2 Embedded Characteristics

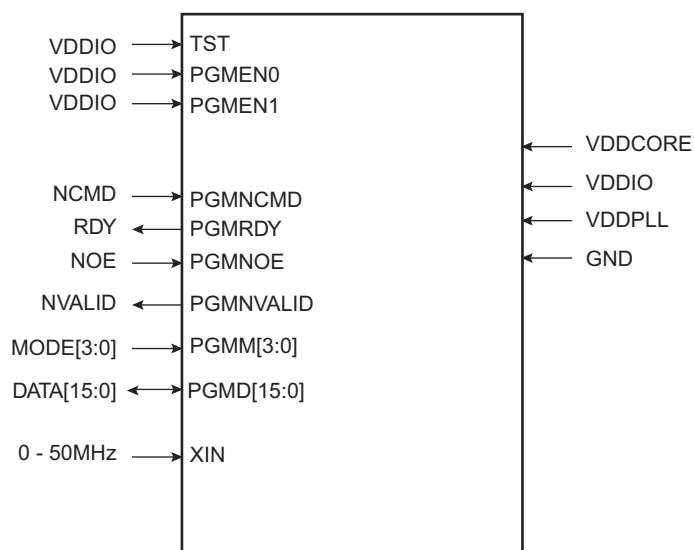
- Programming Mode for High-volume Flash Programming Using Gang Programmer
  - Offers Read and Write Access to the Flash Memory Plane
  - Enables Control of Lock Bits and General-purpose NVM Bits
  - Enables Security Bit Activation
  - Disabled Once Security Bit is Set
- Parallel Fast Flash Programming Interface
  - Provides an 16-bit Parallel Interface to Program the Embedded Flash
  - Full Handshake Protocol

### 20.3 Parallel Fast Flash Programming

#### 20.3.1 Device Configuration

In Fast Flash Programming Mode, the device is in a specific test mode. Only a certain set of pins is significant. The rest of the PIOs are used as inputs with a pull-up. The crystal oscillator is in bypass mode. Other pins must be left unconnected.

Figure 20-1. SAM4Nx/B/C Parallel Programming Interface





23.5.7 Transmit Next Pointer Register

Name: PERIPH\_TNPR

Access: Read-write

31	30	29	28	27	26	25	24
TXNPTR							
23	22	21	20	19	18	17	16
TXNPTR							
15	14	13	12	11	10	9	8
TXNPTR							
7	6	5	4	3	2	1	0
TXNPTR							

• TXNPTR: Transmit Next Pointer

TXNPTR contains next transmit buffer address.  
When a half duplex peripheral is connected to the PDC, RXNPTR = TXNPTR.

## 25.16.5 PMC Peripheral Clock Disable Register 0

**Name:** PMC\_PCDR0

**Address:** 0x400E0414

**Access:** Write-only

31	30	29	28	27	26	25	24
PID31	PID30	PID29	PID28	PID27	PID26	PID25	PID24
23	22	21	20	19	18	17	16
PID23	PID22	PID21	PID20	PID19	PID18	PID17	PID16
15	14	13	12	11	10	9	8
PID15	PID14	PID13	PID12	PID11	PID10	PID9	PID8
7	6	5	4	3	2	1	0
–	–	–	–	–	–	–	–

This register can only be written if the WPEN bit is cleared in “PMC Write Protect Mode Register” .

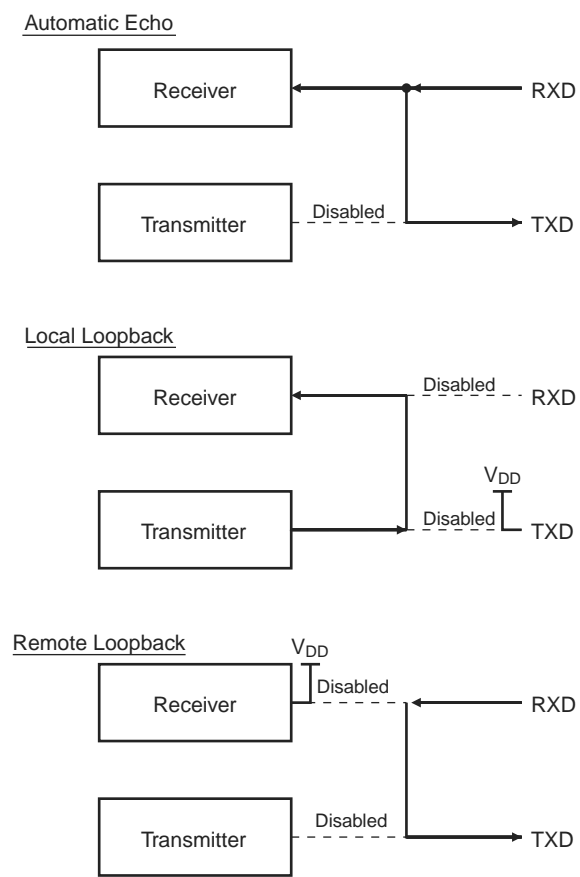
- **PIDx: Peripheral Clock x Disable**

0 = No effect.

1 = Disables the corresponding peripheral clock.

Note: To get PIDx, refer to identifiers as defined in the section “Peripheral Identifiers” in the product datasheet.

**Figure 30-11. Test Modes**



### 31.8.8 USART Interrupt Disable Register (SPI\_MODE)

**Name:** US\_IDR (SPI\_MODE)

**Address:** 0x4002400C (0), 0x4002800C (1), 0x4002C00C (2)

**Access:** Write-only

31	30	29	28	27	26	25	24
–	–	–	–	–	–	–	–
23	22	21	20	19	18	17	16
–	–	–	–	–	–	–	–
15	14	13	12	11	10	9	8
–	–	–	RXBUFF	TXBUFE	UNRE	TXEMPTY	–
7	6	5	4	3	2	1	0
–	–	OVRE	ENDTX	ENDRX	–	TXRDY	RXRDY

This configuration is relevant only if USART\_MODE=0xE or 0xF in “USART Mode Register” on page 633.

- **RXRDY:** RXRDY Interrupt Disable
- **TXRDY:** TXRDY Interrupt Disable
- **OVRE:** Overrun Error Interrupt Disable
- **TXEMPTY:** TXEMPTY Interrupt Disable
- **UNRE:** SPI Underrun Error Interrupt Disable

0: No effect

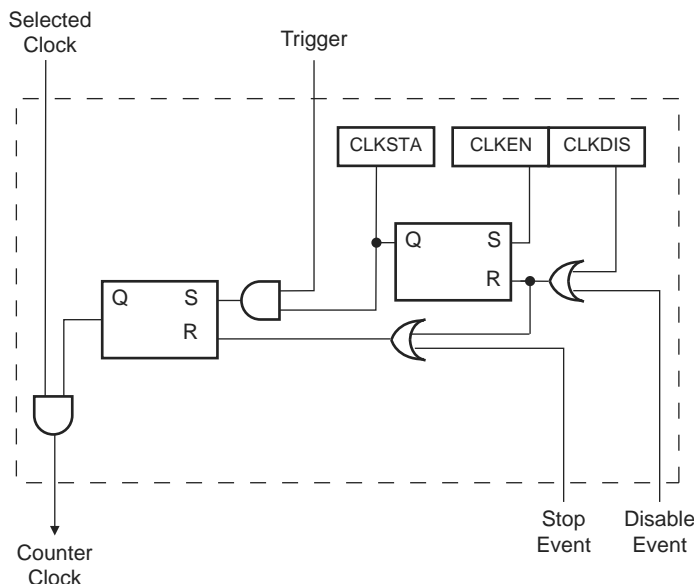
1: Disables the corresponding interrupt.

### 32.6.4 Clock Control

The clock of each counter can be controlled in two different ways: it can be enabled/disabled and started/stopped. See Figure 32-4.

- The clock can be enabled or disabled by the user with the CLKEN and the CLKDIS commands in the TC Channel Control Register (TC\_CCR). In Capture mode it can be disabled by an RB load event if LDBDIS is set to 1 in the TC\_CMR. In Waveform mode, it can be disabled by an RC Compare event if CPCDIS is set to 1 in TC\_CMR. When disabled, the start or the stop actions have no effect: only a CLKEN command in the TC\_CCR can re-enable the clock. When the clock is enabled, the CLKSTA bit is set in the TC\_SR.
- The clock can also be started or stopped: a trigger (software, synchro, external or compare) always starts the clock. The clock can be stopped by an RB load event in Capture mode (LDBSTOP = 1 in TC\_CMR) or an RC compare event in Waveform mode (CPCSTOP = 1 in TC\_CMR). The start and the stop commands are effective only if the clock is enabled.

Figure 32-4. Clock Control



### 32.6.5 Operating Modes

Each channel can operate independently in two different modes:

- Capture mode provides measurement on signals.
- Waveform mode provides wave generation.

The TC operating mode is programmed with the WAVE bit in the TC\_CMR.

In Capture mode, TIOA and TIOB are configured as inputs.

In Waveform mode, TIOA is always configured to be an output and TIOB is an output if it is not selected to be the external trigger.

### 32.6.6 Trigger

A trigger resets the counter and starts the counter clock. Three types of triggers are common to both modes, and a fourth external trigger is available to each mode.

Regardless of the trigger used, it will be taken into account at the following active edge of the selected clock. This means that the counter value can be read differently from zero just after a trigger, especially when a low frequency signal is selected as the clock.

- **LDBDIS: Counter Clock Disable with RB Loading**

0: Counter clock is not disabled when RB loading occurs.

1: Counter clock is disabled when RB loading occurs.

- **ETRGEDG: External Trigger Edge Selection**

Value	Name	Description
0	NONE	The clock is not gated by an external signal.
1	RISING	Rising edge
2	FALLING	Falling edge
3	EDGE	Each edge

- **ABETRG: TIOA or TIOB External Trigger Selection**

0: TIOB is used as an external trigger.

1: TIOA is used as an external trigger.

- **CPCTRG: RC Compare Trigger Enable**

0: RC Compare has no effect on the counter and its clock.

1: RC Compare resets the counter and starts the counter clock.

- **WAVE: Waveform Mode**

0: Capture mode is enabled.

1: Capture mode is disabled (Waveform mode is enabled).

- **LDRA: RA Loading Edge Selection**

Value	Name	Description
0	NONE	None
1	RISING	Rising edge of TIOA
2	FALLING	Falling edge of TIOA
3	EDGE	Each edge of TIOA

- **LDRB: RB Loading Edge Selection**

Value	Name	Description
0	NONE	None
1	RISING	Rising edge of TIOA
2	FALLING	Falling edge of TIOA
3	EDGE	Each edge of TIOA

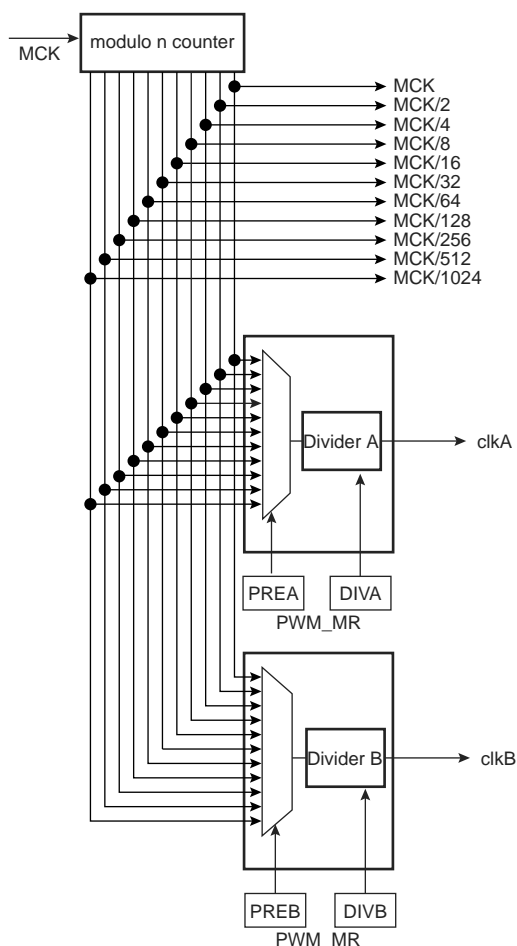
## 33.6 Functional Description

The PWM macrocell is primarily composed of a clock generator module and channels.

- Clocked by the system clock, MCK, the clock generator module provides 13 clocks.
- Each channel can independently choose one of the clock generator outputs.
- Each channel generates an output waveform with attributes that can be defined independently for each channel through the user interface registers.

### 33.6.1 PWM Clock Generator

Figure 33-2. Functional View of the Clock Generator Block Diagram



**Caution:** Before using the PWM macrocell, the programmer must first enable the PWM clock in the Power Management Controller (PMC).

The PWM macrocell master clock, MCK, is divided in the clock generator module to provide different clocks available for all channels. Each channel can independently select one of the divided clocks.

The clock generator is divided in three blocks:

- a modulo n counter which provides 11 clocks:  $F_{MCK}$ ,  $F_{MCK}/2$ ,  $F_{MCK}/4$ ,  $F_{MCK}/8$ ,  $F_{MCK}/16$ ,  $F_{MCK}/32$ ,  $F_{MCK}/64$ ,  $F_{MCK}/128$ ,  $F_{MCK}/256$ ,  $F_{MCK}/512$ ,  $F_{MCK}/1024$
- two linear dividers (1, 1/2, 1/3,... 1/255) that provide two separate clocks: clkA and clkB

### 34.7.18 ADC Channel Data Register

**Name:** ADC\_CDRx [x=0..16]

**Address:** 0x40038050

**Access:** Read-write

31	30	29	28	27	26	25	24
–	–	–	–	–	–	–	–
23	22	21	20	19	18	17	16
–	–	–	–	–	–	–	–
15	14	13	12	11	10	9	8
–	–	–	–	DATA			
7	6	5	4	3	2	1	0
DATA							

- **DATA: Converted Data**

The analog-to-digital conversion data is placed into this register at the end of a conversion and remains until a new conversion is completed. The Convert Data Register (CDR) is only loaded if the corresponding analog channel is enabled.



Figure 36-9. SAM4N8/16 Active Power Consumption with VDDCORE @ 1.2V, T<sub>A</sub> = 25°C

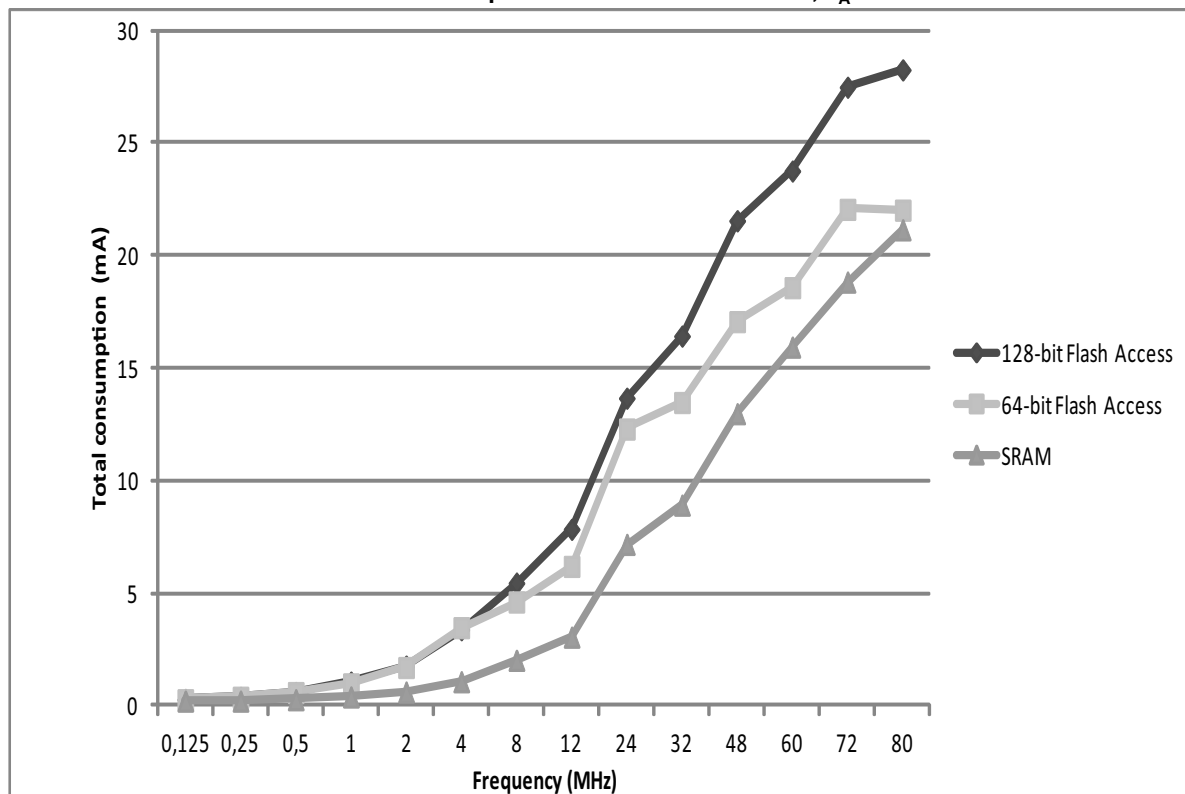


Table 36-16 gives Active mode current consumption in conditions:

- VDDCORE at 1.2V
- $T_A = -40^{\circ}\text{C}$

**Table 36-16. CoreMark Active Power Consumption**

Core Clock (MHz)	CoreMark						Unit
	128-bit Flash Access <sup>(1)</sup>		64-bit Flash Access <sup>(1)</sup>		SRAM		
	AMP1	AMP2	AMP1	AMP2	AMP1	AMP2	
80	11.84	17.21	8.52	13.51	8.56	12.16	mA
72	11.50	16.68	8.58	13.22	7.8	11.04	
60	9.81	14.40	7.34	11.50	6.62	9.37	
48	9.16	12.77	6.80	10.32	5.41	7.67	
32	6.24	9.68	5.46	8.39	3.71	5.36	
24	5.43	9.43	5.02	7.70	2.85	4.51	
12	3.30	4.74	2.59	3.71	1.46	1.90	
8	2.25	3.57	1.81	2.89	0.51	1.42	
4	1.03	2.84	0.96	2.82	0.51	0.96	
2	0.61	1.56	0.52	1.50	0.28	0.75	
1	0.34	1.10	0.29	1.01	0.17	0.64	
0.5	0.19	0.78	0.18	0.77	0.12	0.58	
0.25	0.14	0.66	0.12	0.63	0.09	0.56	
0.125	0.10	0.56	0.09	0.56	0.09	0.56	

Note: 1. Flash Wait State (FWS) in EEFC\_FMR adjusted versus core frequency

### 36.4.6 3 to 20 MHz Crystal Characteristics

**Table 36-24. Crystal Characteristics**

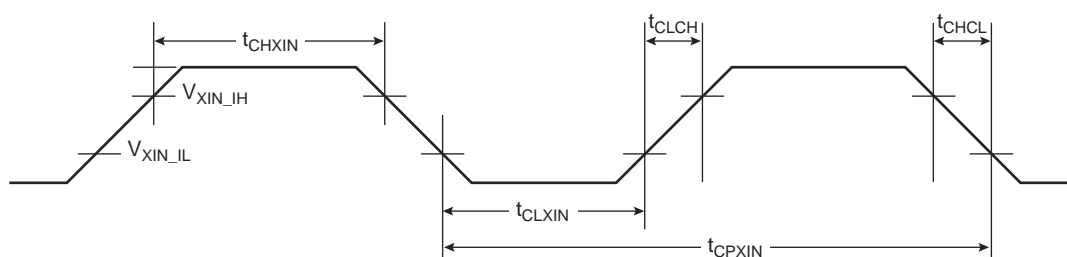
Symbol	Parameter	Conditions	Min	Typ	Max	Unit
ESR	Equivalent Series Resistor (Rs)	Fundamental @ 3 MHz Fundamental @ 8 MHz Fundamental @ 16 MHz Fundamental @ 20 MHz			200 100 80 50	$\Omega$
$C_m$	Motional Capacitance				8	fF
$C_{SHUNT}$	Shunt Capacitance				7	pF
$C_{LOAD}$	Load Capacitance	Max external capacitors: 17 pF	12.5		17.5	pF

### 36.4.7 3 to 20 MHz XIN Clock Input Characteristics in Bypass Mode

**Table 36-25. XIN Clock Electrical Characteristics (In Bypass Mode)**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$1/(t_{CPXIN})$	XIN Clock Frequency	3–20 MHz crystal oscillator is in Bypass mode			20	MHz
$t_{CPXIN}$	XIN Clock Period		50			ns
$t_{CHXIN}$	XIN Clock High Half-period		20			ns
$t_{CLXIN}$	XIN Clock Low Half-period		20			ns
$t_{CLCH}$	Rise Time		15			ns
$t_{CHCL}$	Fall Time		15			ns
$V_{XIN\_IL}$	$V_{XIN}$ Input Low-level Voltage		-0.3		$[0.8V:0.3 \times V_{DDIO}]$	V
$V_{XIN\_IH}$	$V_{XIN}$ Input High-level Voltage		$[2.0V:0.7 \times V_{DDIO}]$		$V_{VDDIO} + 0.3V$	V

**Figure 36-12. XIN Clock Timing**



## 36.8 Voltage Reference Description

Note: Unless otherwise noted, Reference Voltage must be decoupled externally with large capacitors: 1  $\mu$ F/10 nF.

**Table 36-38. Voltage Reference Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{REFINT}$	Reference Voltage Internal Available		2		3.4	V
$V_{REF}$	Reference Voltage		1.6		3.4	V
$V_{REFACC}$	Reference Voltage Accuracy		-50		50	mV
$I_{VDD}$	Current Consumption	Active mode		20	30	$\mu$ A
$I_{DDBIAS}$	Current Consumption	Voltage reference Off, ADC On or DAC On		7	10	$\mu$ A
$I_{DD(standby)}$	Standby Current	VDD @ 3.6V, leakage current			700	nA
$I_{VDDI}$	Current Consumption, Digital				70	nA
$I_{VDDI(standby)}$	Standby Current Consumption, Digital				50	nA
$t_{START}$	Startup time	VDD @ 2V VDD @ 3V VDD @ 3.6V		50	100 70 40	$\mu$ s

## 36.9 Temperature Sensor

The temperature sensor is connected to channel 15 of the ADC.

The temperature sensor provides an output voltage ( $V_{O\_TS}$ ) that is proportional to absolute temperature (PTAT).  $V_{O\_TS}$  linearly varies with a temperature slope  $dV_{O\_TS}/dT = 4.72$  mV/ $^{\circ}$ C.

$V_{O\_TS}$  equals 1.44V at  $T_A$  27 $^{\circ}$ C, with a  $\pm 60$  mV accuracy. The  $V_{O\_TS}$  slope versus temperature  $dV_{O\_TS}/dT = 4.72$  mV/ $^{\circ}$ C only shows a  $\pm 7\%$  slight variation over process, mismatch and supply voltage.

The user needs to calibrate it (offset calibration) at ambient temperature to eliminate the  $V_{O\_TS}$  spread at ambient temperature ( $\pm 15\%$ ).

**Table 36-39. Temperature Sensor Characteristics**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
	Power Supply		2.4	3.3	3.6	V
$V_{O\_TS}$	Output Voltage	$T_A = 27^{\circ}\text{C}$		1.44		V
$V_{O\_TS(accuracy)}$	Output Voltage Accuracy	$T_A = 27^{\circ}\text{C}$ (needs to be calibrated in application)	-60		60	mV
$dV_{O\_TS}/dT$	Temperature Sensitivity (Slope Voltage vs Temperature)			4.72		mV/ $^{\circ}$ C
	Slope Accuracy	Over temperature range -40 to 85 $^{\circ}$ C	-7		7	%
	Temperature Accuracy	After offset calibration Over temperature range -40 to 85 $^{\circ}$ C	-8		+8	$^{\circ}$ C
		After offset calibration Over temperature range 0 to 80 $^{\circ}$ C	-4		+4	$^{\circ}$ C
$t_{START}$	Startup Time			5	10	$\mu$ s
$I_{VDDCORE}$	Current Consumption	Active mode	50	70	80	$\mu$ A
		Standby mode			1	

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